AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Currently amended) An optoelectronic component based on a surface mount technology, said optoelectronic component comprising:

an electrically conductive frame to form a base for an assembly;

at least one optoelectronic chip mounted on said base;

an electrical connection between said optoelectronic chip and said electrically conductive frame by wiring means;

soldering terminals [[which]] provided by the base are part of said electrically conductive frame and are exposed at bottom and side portions of said component; and

a series of grooves and wings crafted in said electrically conductive frame to enhance anchorage and minimize an occurrence of de-lamination[[;]],

wherein said electrically conductive frame is entirely encapsulated with a transparent or translucent material to enable optical radiation to be transmitted or received via said optoelectronic component[[;]], and

wherein said soldering terminals do not extend beyond an outline of said encapsulation material.

2-9. (Canceled)

10. (Previously presented) The optoelectronic component as claimed in claim 1, wherein said electrically conductive frame is made of a metal.

11. (Previously presented) The optoelectronic component as claimed in claim 1, wherein a lens structure is incorporated as part of said encapsulation material.

12. (Previously presented) The optoelectronic component as claimed in claim 1, wherein a multiple lens structure is incorporated as part of said encapsulation material.

13. (Previously presented) The optoelectronic component as claimed in claim 1, wherein a cavity is formed within said electrically conductive frame and is used to attach said optoelectronic chip within said cavity and serve as a reflector.

14. (Canceled)